



### General Description

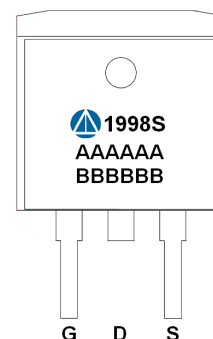
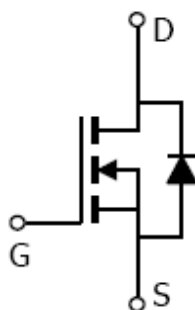
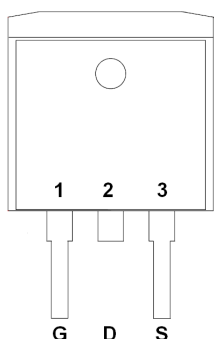
AFN1998S, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

These devices are particularly suited for low voltage power management, and low in-line power loss are needed in commercial industrial surface mount applications.

### Features

- 100V/10A,  $R_{DS(ON)} = 21m\Omega @ V_{GS} = 10V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- TO-263-2L package design

### Pin Description ( TO-263-2L )



### Application

- DC/DC Primary Side Switch
- POL Synchronous buck converter
- LED Backlight for LCD TV industrial

### Pin Define

Pin	Symbol	Description
1	G	Gate
2	D	Drain
3	S	Source

### Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFN1998ST263RG	1998S AAAAAA BBBBBB	TO-263-2L	Tape & Reel	800 EA

- ※ A Lot code
- ※ B Date code
- ※ AFN1998ST263RG : Tube ; Pb- Free ; Halogen -Free



**Absolute Maximum Ratings**

( $T_A=25^{\circ}\text{C}$  Unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	100	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current( $T_J=150^{\circ}\text{C}$ )	$I_D$	$T_C=25^{\circ}\text{C}$	50
		$T_C=70^{\circ}\text{C}$	40
Pulsed Drain Current	$I_{DM}$	60	A
Continuous Source Current(Diode Conduction)	$I_S$	50	
Single Pulse Avalanche Current	$I_{AS}$	40	
Power Dissipation	$P_D$	$T_C=25^{\circ}\text{C}$	100
		$T_A=25^{\circ}\text{C}$	3.1
Operating Junction Temperature	$T_J$	150	$^{\circ}\text{C}$
Storage Temperature Range	$T_{STG}$	-55/150	$^{\circ}\text{C}$
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	62.5	$^{\circ}\text{C}/\text{W}$

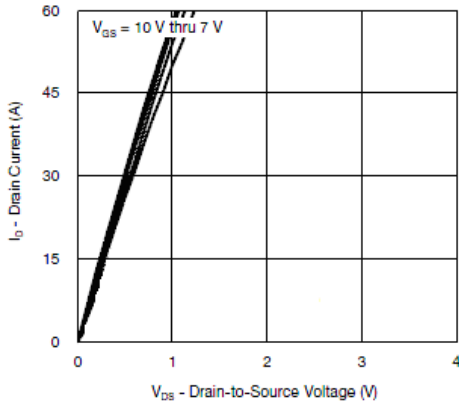
**Electrical Characteristics**

( $T_A=25^{\circ}\text{C}$  Unless otherwise noted)

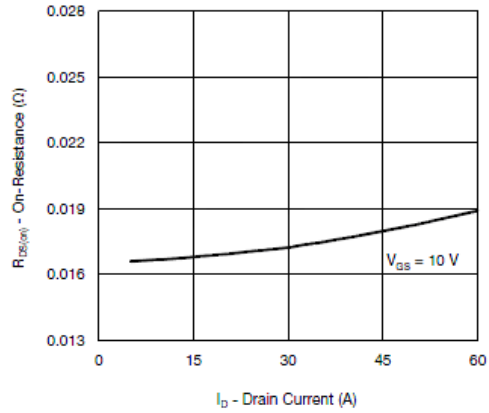
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu\text{A}$	100			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2.5		4.5	
Gate Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=80V, V_{GS}=0V$			1	uA
		$V_{DS}=80V, V_{GS}=0V$ $T_J=85^{\circ}\text{C}$			30	
On-State Drain Current	$I_{D(on)}$	$V_{DS} \geq 10V, V_{GS}=10V$	20			A
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=10A$		17.7	21	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=20V, I_D=10A$		40		S
Diode Forward Voltage	$V_{SD}$	$I_S=20A, V_{GS}=0V$		0.8	1.3	V
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS}=50V, V_{GS}=10V$ $I_D \cong 10A$		45	90	nC
Gate-Source Charge	$Q_{gs}$			11		
Gate-Drain Charge	$Q_{gd}$			16		
Input Capacitance	$C_{iss}$	$V_{DS}=50V, V_{GS}=0V$ $f=1\text{MHz}$		2100		pF
Output Capacitance	$C_{oss}$			230		
Reverse Transfer Capacitance	$C_{rss}$			120		
Turn-On Time	$t_{d(on)}$	$V_{DD}=20V, R_L=2\Omega$ $I_D \cong 8A, V_{GEN}=10V$ $R_G=1\Omega$		10	20	ns
	$t_r$			10	20	
Turn-Off Time	$t_{d(off)}$			25	50	
	$t_f$			8	15	



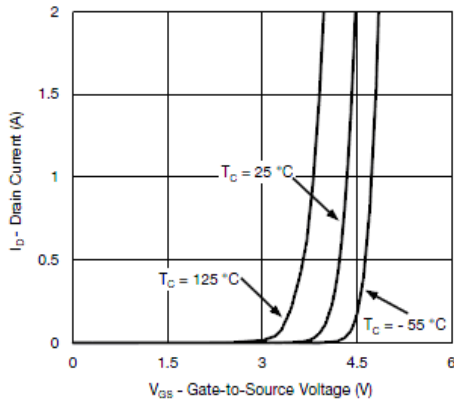
## Typical Characteristics



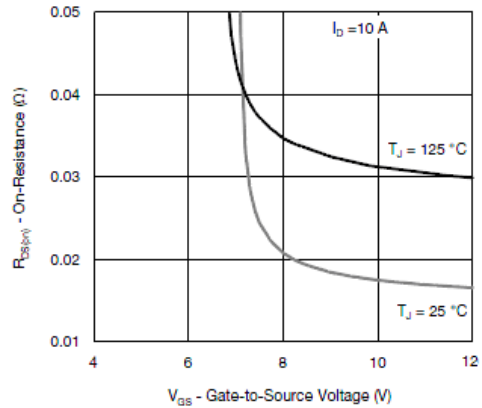
Output Characteristics



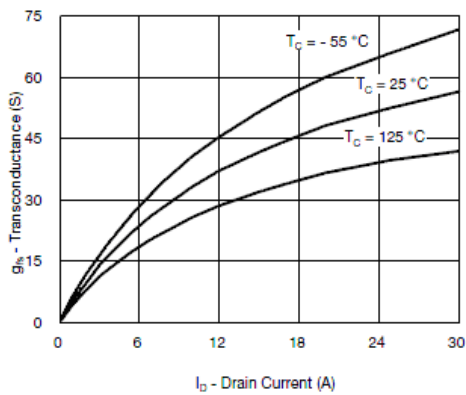
On-Resistance vs. Drain Current



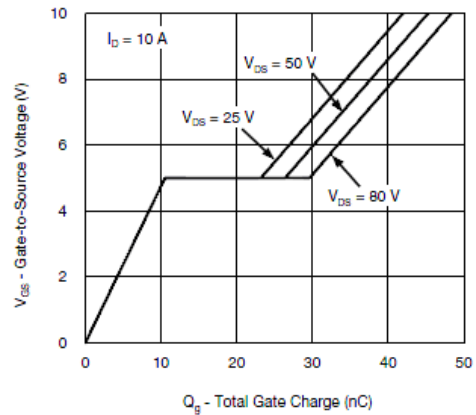
Transfer Characteristics



On-Resistance vs. Gate-to-Source Voltage



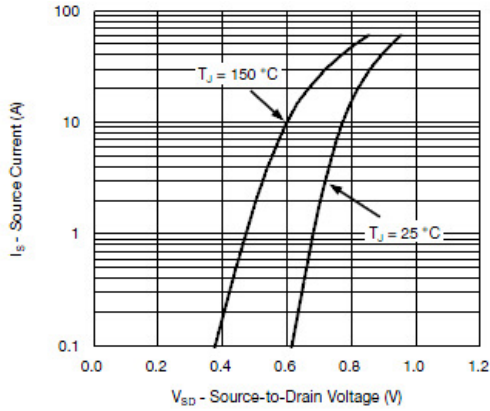
Transconductance



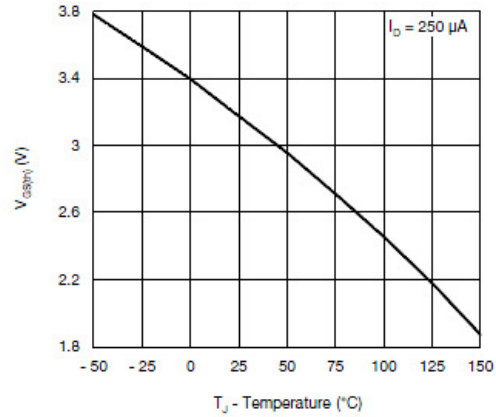
Gate Charge



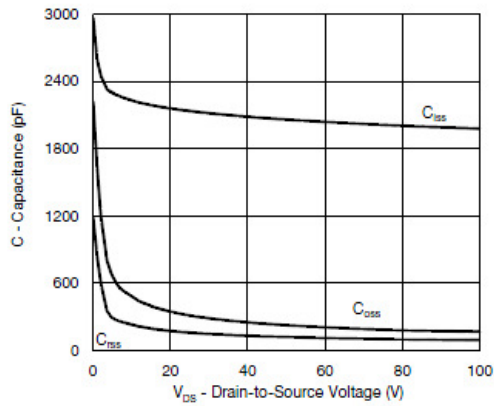
## Typical Characteristics



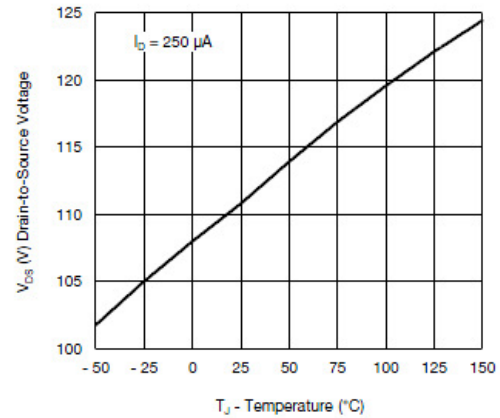
Source-Drain Diode Forward Voltage



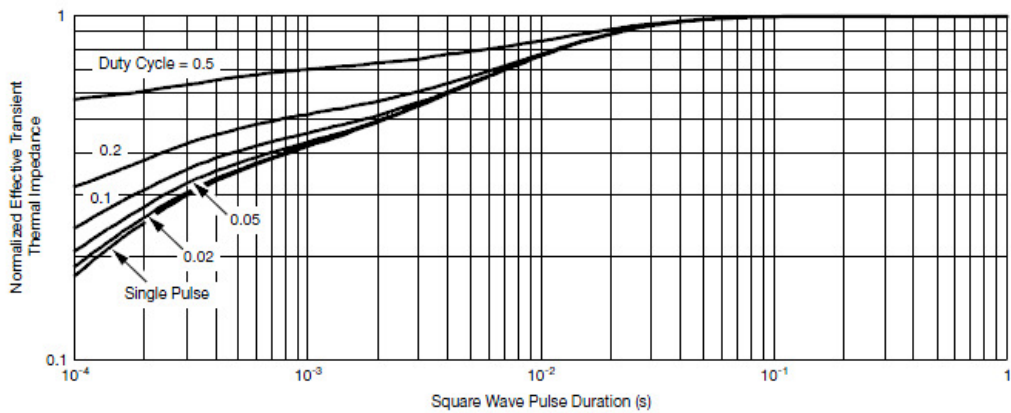
Threshold Voltage



Capacitance



Drain Source Breakdown vs. Junction Temperature



Normalized Thermal Transient Impedance, Junction-to-Case



## Typical Characteristics

Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

